

Contact Resistance Limits of Ohmic Contacts to Thin Semiconductor Channels

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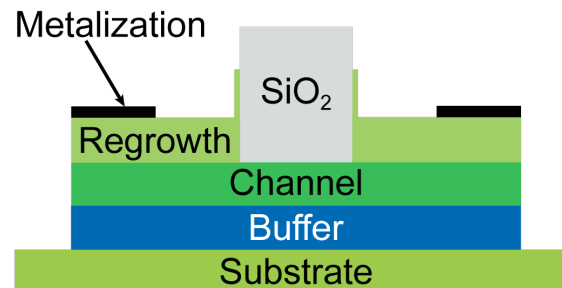


Introduction:

- InGaAs MOSFETs need contact resistance of $< 10 \Omega \mu\text{m}$ for $L_g=L_c=20 \text{ nm}$ ¹
- We show epitaxially regrown source-drain contacts as low as $65 \Omega \mu\text{m}$ to thin channels and $12.5 \Omega \mu\text{m}$ to thick channels
- *There is a minimum measurable contact resistance for a given n_s (channel thickness)*
- Limit independent of material system & should not impact transistor performance

Our Approach:

- Homoepitaxial regrowth → best regrowth-channel contact resistance
- InAs → best metal-regrowth contact resistance²
- Demonstrate existence of relationship between channel n_s and contact resistance extraction



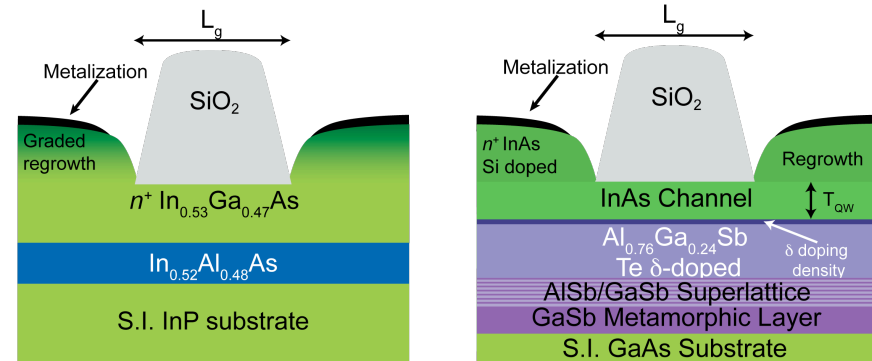
¹ M. J. W. Rodwell et al, IPRM (2008)

² A. Baraskar et al, IPRM (2010).

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Experimental Details:

- Channels of varying n_s grown by MBE
 - 15 nm InAs and 100 nm n^+ InGaAs channel
- Homoepitaxial regrowth by MBE
 - n^+ InAs and graded n^+ InGaAs to n^+ InAs
- TLM for contact resistance measurement



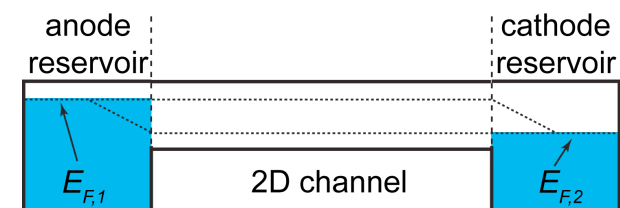
Experimental Results

Thickness	Regrowth	R_{RG-C} ($\Omega \mu m$)	R_{M-RG} ($\Omega \mu m$)
15 nm InAs	n^+ InAs	~ 65 ($130 R_{S+D}$)	~ 3.0
100 nm n^+ $In_{0.53}Ga_{0.47}As$	Graded from $n^+ In_{0.53}Ga_{0.47}As$ to $n^+ InAs$	~ 12.5	~ 3.0

Theory Results:

- 15 nm InAs device: theoretical min. $R_C = 80 \Omega \mu m$
- Our regrowth is within a factor of 2 of this limit
- 2-D generalization from Landauer:^{*}

$$G = \frac{q^2 2^{1/2}}{\hbar \pi^{3/2}} \sum_i n_{s,i}^{1/2}$$



^{*}R. Landauer, IBM J. Res. Dev. 1, 223 (1957).

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Conclusions:

- There is a minimum measurable contact resistance from a TLM structure
- $R_{C,min}$ is a function of channel sheet carrier density
- Limit applies to all materials systems not just $\text{In}_x\text{Ga}_{1-x}\text{As}$
- Minimum resistance is **not** an additional parasitic resistance if integrated into an FET
- n^+ InAs regrowth $R_S+R_D=130 \Omega \mu m$ is within a factor of 2 of theoretical $80 \Omega \mu m$
- Graded regrowth not limited by n_s shows $R_S=R_D=12.4 \Omega \mu m$

TLM extraction of R_C on channels with small n_s not representative of contact resistance

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